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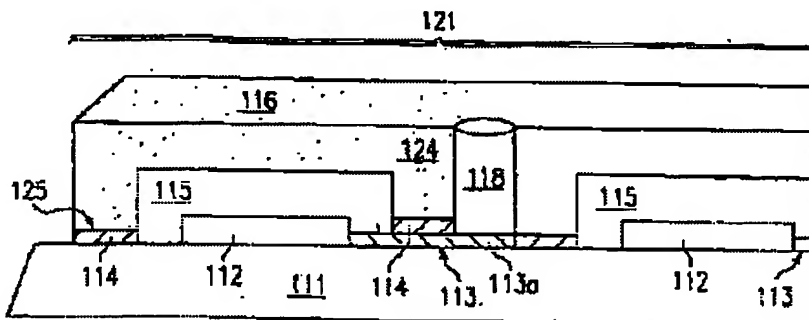
(30) Priority: 04.10.99 US 1999 157560	(71) Applicant: TEXAS INSTR INC <TI>
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(54) IMPROVED MEMS WAFER-LEVEL PACKAGE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a method for packaging micro electro-mechanical system(MEMS) which is built on a wafer on the smallest scale and under optimum conditions, by using current manufacturing technology before dividing it into individual chips.

SOLUTION: Enclosed cavities are formed by bonding a silicon cap wafer 116 provided with cavities 115, in each of which MEMS can be housed by etching and a silicon wafer 111, on which active circuits 112 are built by a thin film 114 of glass and a cavity sidewall 125. A conductor 113 is formed of a minimum length and a bonding wire is connected to a contact pad 113a through a hole 118, when the conductor is divided and ultimately incorporated in the system.



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